2SK1306

Silicon N-Channel MOS FET

HITACHI

ADE-208-1264 (Z) 1st. Edition Mar. 2001

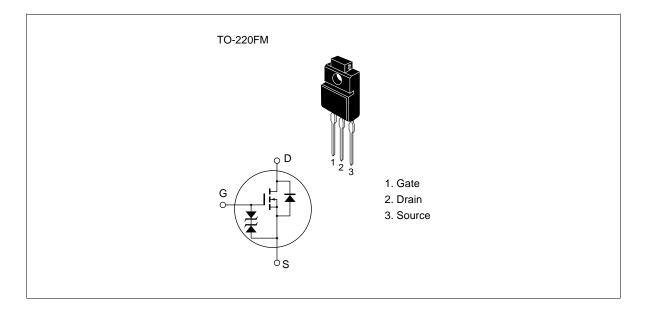
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device
 - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline





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Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{ t DSS}$	100	V
Gate to source voltage	$V_{\sf GSS}$	±20	V
Drain current	I _D	15	A
Drain peak current	l _{D(pulse)} *1	60	Α
Body to drain diode reverse drain current	I _{DR}	15	Α
Channel dissipation	Pch*2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW 10 µs, duty cycle 1%

2. Value at $T_c = 25$ °C

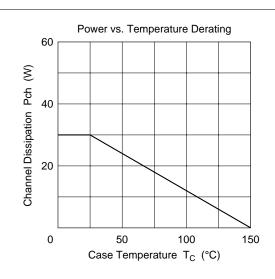
Electrical Characteristics ($Ta = 25^{\circ}C$)

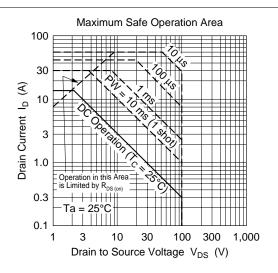
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		_	250	μΑ	$V_{DS} = 80 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{\text{DS(on)}}$	_	0.10	0.13		$I_D = 8 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
		_	0.13	0.18		$I_D = 8 \text{ A}, V_{GS} = 4 \text{ V}^{*1}$
Forward transfer admittance	yfs	7	11	_	S	$I_D = 8 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	860	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	340	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	100	_	pF	
Turn-on delay time	t _{d(on)}	_	10	_	ns	$I_D = 8 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	_	70	_	ns	$R_L = 3.75$
Turn-off delay time	$t_{\text{d(off)}}$	_	180	_	ns	_
Fall time	t _f	_	100	_	ns	
Body to drain diode forward voltage	V_{DF}	_	1.3	_	V	I _F = 15 A, V _{GS} = 0
Body to drain diode reverse recovery time	t _{rr}	_	250	_	ns	$I_F = 15 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu\text{s}$

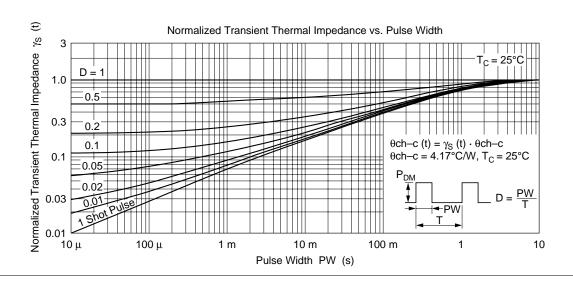
Note: 1. Pulse test

See characteristic curves of 2SK1301.

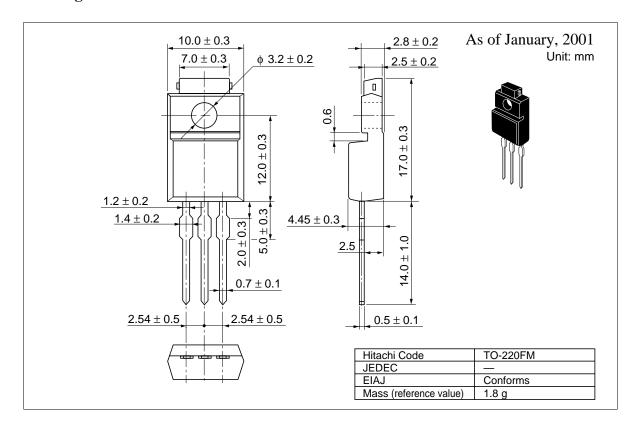
2SK1306







Package Dimensions



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